

In the Claims: (strikethrough parts deleted and underlined parts added)

Claims 5, 6, 7, 8, 9 and 10 have already been deleted without prejudice.

1. (Currently Amended) A thermal management socket system, comprising:
a thermal management unit having a chamber, wherein said chamber is capable of receiving at least one electronic device;

a plurality of first connectors within said chamber of said thermal management unit, wherein said first connectors may be electrically coupled with a corresponding plurality of device connectors of said at least one electronic device; and

a plurality of second connectors extending out from said thermal management unit, wherein said second connectors are electrically coupled to said first connectors and wherein said second connectors may be removably and electrically coupled to a socket on a board.

2. (Currently Amended) The thermal management socket system of Claim 1, including a liquid thermal management system coupled to said chamber for thermally managing said at least one electronic device.

3. (Original) The thermal management socket system of Claim 2, wherein said liquid thermal management system is comprised of spray cooling.

4. (Original) The thermal management socket system of Claim 2, wherein said liquid thermal management system is comprised of liquid immersion.

5. (Canceled)

6. (Canceled)

7. (Canceled)

8. (Canceled)

9. (Canceled)

10. (Canceled)

11. (Currently Amended) The thermal management socket system of Claim 1, wherein said first connectors are each comprised of a receptacle structure capable of receiving a corresponding device connector from said at least one electronic device.

12. (Previously Amended) The thermal management socket system of Claim 1, wherein said first connectors are each comprised of a raised structure capable of electrically coupling with said at least one electronic device utilizing a ball grid array or a land grid array.

13. (Original) The thermal management socket system of Claim 1, wherein said thermal management unit is comprised of a base portion containing said first connectors and said second connectors, and a cap member removably connectable to said base portion for defining said chamber.

14. (Previously Amended) A method of utilizing a thermal management unit, said method comprising the steps of:

providing a thermal management unit, wherein said thermal management unit is capable of receiving at least one electronic device; and

electrically and detachably coupling said thermal management unit to a socket unit, wherein said socket unit is permanently attached to a board.

15. (Currently Amended) The method of utilizing a thermal management unit of Claim 14, including the step of positioning and electrically coupling said at least one electronic device within said thermal management unit.

16. (Previously Amended) The method of utilizing a thermal management unit of Claim 15, including the step of sealing said thermal management unit about said at least one electronic device.

17. (Original) The method of utilizing a thermal management unit of Claim 16, wherein said step of sealing said thermal management unit comprises attaching a cap member in a sealed manner to a base portion of said thermal management unit.

18. (Currently Amended) The method of utilizing a thermal management unit of Claim 14, wherein said thermal management unit utilizes liquid thermal management system for thermally managing said at least one electronic device positioned within said thermal management unit.

19. (Currently Amended) A method of utilizing a thermal management unit, said method comprising the steps of:

providing a thermal management unit, wherein said thermal management unit is capable of receiving at least one electronic device and wherein said thermal management unit is capable of electrically and detachably coupling to a socket unit permanently attached to a board; and

positioning and electrically coupling said at least one electronic device within said thermal management unit.

20. (Previously Amended) The method of utilizing a thermal management unit of Claim 19, including the step of sealing said thermal management unit about said at least one electronic device.

21. (Original) The method of utilizing a thermal management unit of Claim 20, wherein said step of sealing said thermal management unit comprises attaching a cap member in a sealed manner to a base portion of said thermal management unit.

22. (Previously Amended) The method of utilizing a thermal management unit of Claim 19, wherein said thermal management unit utilizes liquid thermal management system for thermally managing said at least one electronic device positioned within said thermal management unit.

23. (Currently Amended) A method of assembling a thermal management system for thermally managing at least one electronic device, said method comprising the steps of:

providing a board including at least one socket permanently attached to said board;

providing a thermal management unit including a chamber, a plurality of first connectors within said chamber, and a plurality of second connectors extending out from said thermal management unit, wherein said second connectors are electrically coupled to said first connectors;

positioning at least one electronic device within said chamber of said thermal management unit and electrically coupling said at least one electronic device to said plurality of first connectors; and

electrically and detachably coupling said second connectors to said at least one socket.

24. (Previously Added) The method of assembling a thermal management system of Claim 23, including the step of fluidly connecting said thermal management unit to a liquid thermal management system.

25. (Currently Amended) A thermal management apparatus for thermally managing at least one electronic device, comprising a thermal management unit capable of receiving at least one electronic device, said thermal management unit including a plurality of first connectors, and a plurality of second connectors electrically coupled to said first connectors and extending out from said thermal management unit, wherein said second connectors are electrically and removably coupled to a socket on a board.

26. (Previously Added) The thermal management apparatus of Claim 25, including a liquid thermal management system coupled to said thermal management unit.

27. (Previously Added) The thermal management apparatus of Claim 26, wherein said liquid thermal management system is comprised of spray cooling.

28. (Previously Added) The thermal management apparatus of Claim 26, wherein said liquid thermal management system is comprised of liquid immersion.